

# Hyper Micro SIDELED Hyper-Bright LED

LS Y876, LA Y876, LO Y876, LY Y876



## Vorläufige Daten / Preliminary Data

### Besondere Merkmale

- **Gehäusotyp:** weißes SMT-Gehäuse
- **Besonderheit des Bauteils:** kleine Bauform mit extrem breiter Abstrahlcharakteristik; ideal für Einkopplungen in Lichtleiter
- **Wellenlänge:** 633 nm (super-rot), 615 nm (amber), 606 nm (orange), 587 nm (gelb)
- **Abstrahlwinkel:** Lambertscher Strahler (120°)
- **Technologie:** InGaAlP
- **optischer Wirkungsgrad:** 9 lm/W (gelb, orange, amber), 5 lm/W (super-rot)
- **Gruppierungsparameter:** Lichtstärke
- **Verarbeitungsmethode:** für alle SMT-Bestücktechniken geeignet
- **Lötmethode:** IR Reflow Löten und Wellenlöten (TTW)
- **Vorbehandlung:** nach JEDEC Level 2
- **Gurtung:** 8 mm Gurt mit 3000/Rolle, ø180 mm oder 10000/Rolle, ø330 mm

### Anwendungen

- optimale Einkopplung in Lichtleiter
- Hinterleuchtung (LCD, Mobiltelefone, Tasten, Allgemeinbeleuchtung, Werbebeleuchtung)
- Signal- und Symbolleuchten
- Automobilbereich (z. B. Instrumentenbeleuchtung)

### Features

- **package:** white SMT package
- **feature of the device:** small package with extremely wide viewing angle; ideal for coupling in light guides
- **wavelength:** 633 nm (super-red), 615 nm (amber), 606 nm (orange), 587 nm (yellow)
- **viewing angle:** Lambertian Emitter (120°)
- **technology:** InGaAlP
- **optical efficiency:** 9 lm/W (yellow, orange, amber), 5 lm/W (super-red)
- **grouping parameter:** luminous intensity
- **assembly methods:** suitable for all SMT assembly methods
- **soldering methods:** IR reflow soldering and TTW soldering
- **preconditioning:** acc. to JEDEC Level 2
- **taping:** 8 mm tape with 3000/reel, ø180 mm or 10000/reel, ø330 mm

### Applications

- optimized coupling into light guides
- backlighting (LCD, cellular phones, keys, general lightning, illuminated advertising)
- signal and symbol luminaire
- automotive (e. g. car radio backlighting)

Type	Emissions- farbe	Farbe der Lichtaustritts- fläche	Lichtstärke	Lichtstrom	Bestellnummer
Type	Color of Emission	Color of the Light Emitting Area	Luminous Intensity $I_F = 20 \text{ mA}$ $I_V \text{ (mcd)}$	Luminous Flux $I_F = 20 \text{ mA}$ $\Phi_V \text{ (lm)}$	Ordering Code
LS Y876-N1P1-1 LS Y876-P1Q2-1	super-red	colorless clear	28.0 ... 56.0 45.0 ... 112.0	120 (typ.) 230 (typ.)	Q62703-Q6195 Q62703-Q6196
LA Y876-P1Q1-1 LA Y876-Q1R2-1	amber	colorless clear	45.0 ... 90.0 71.0 ... 180.0	200 (typ.) 370 (typ.)	Q62703-Q6193 Q62703-Q6194
LO Y876-P2Q2-1 LO Y876-Q2S1-1	orange	colorless clear	56.0 ... 112.0 90.0 ... 224.0	240 (typ.) 440 (typ.)	Q62703-Q6199 Q62703-Q6200
LY Y876-P1Q1-1 LY Y876-Q1R2-1	yellow	colorless clear	45.0 ... 90.0 71.0 ... 180.0	200 (typ.) 370 (typ.)	Q62703-Q6197 Q62703-Q6198

Anm.: -1 gesamter Farbbereich

Die Standardlieferform von Serientypen beinhaltet eine untere bzw. eine obere Familiengruppe, die aus nur 3 bzw. 4 Halbgruppen besteht. Einzelne Halbgruppen sind nicht erhältlich.  
In einer Verpackungseinheit / Gurt ist immer nur eine Halbgruppe enthalten.

Note: -1 Total color tolerance range

The standard shipping format for serial types includes a lower or upper family group of 3 or 4 individual groups. Individual half groups are not available.  
No packing unit / tape ever contains more than one luminous intensity half group..

**Grenzwerte**  
**Maximum Ratings**

Bezeichnung Parameter	Symbol Symbol	Werte Values		Einheit Unit
		LS, LO, LA	LY	
Betriebstemperatur Operating temperature range	$T_{\text{op}}$	– 40 ... + 100		°C
Lagertemperatur Storage temperature range	$T_{\text{stg}}$	– 40 ... + 100		°C
Sperrschichttemperatur Junction temperature	$T_{\text{j}}$	+ 125		°C
Durchlassstrom Forward current	$I_{\text{F}}$	30		mA
Stoßstrom Surge current $t \leq 10 \mu\text{s}$ , $D = 0.005$	$I_{\text{FM}}$	t.b.d.	t.b.d.	A
Sperrspannung Reverse voltage $I_{\text{F}} = 10 \mu\text{A}$	$V_{\text{R}}$	3		V
Leistungsaufnahme Power consumption $T_{\text{A}} \leq 25 \text{ °C}$	$P_{\text{tot}}$	80		mW
Wärmewiderstand Thermal resistance Sperrschicht/Umgebung Junction/ambient Sperrschicht/Löt­pad Junction/solder point Montage auf PC-Board FR 4 (Padgröße $\geq 16 \text{ mm}^2$ ) mounted on PC board FR 4 (pad size $\geq 16 \text{ mm}^2$ )	$R_{\text{th JA}}$    $R_{\text{th JS}}$	630    350		K/W    K/W

**Kennwerte** ( $T_A = 25\text{ °C}$ )**Characteristics**

Bezeichnung Parameter	Symbol Symbol	Werte Values				Einheit Unit
		LS	LA	LO	LY	
Wellenlänge des emittierten Lichtes (typ.) Wavelength at peak emission $I_F = 20\text{ mA}$	$\lambda_{\text{peak}}$	645	622	610	591	nm
Dominantwellenlänge <sup>1)</sup> (typ.) Dominant wavelength <sup>1)</sup> $I_F = 20\text{ mA}$	$\lambda_{\text{dom}}$	633 $\pm 6$	617 $\pm 5$	606 $\pm 6$	587 +8/-7	nm
Spektrale Bandbreite bei 50 % $I_{\text{rel max}}$ (typ.) Spectral bandwidth at 50 % $I_{\text{rel max}}$ $I_F = 20\text{ mA}$	$\Delta\lambda$	16	16	16	15	nm
Abstrahlwinkel bei 50 % $I_V$ (Vollwinkel) (typ.) Viewing angle at 50 % $I_V$	$2\phi$	120	120	120	120	Grad deg.
Durchlassspannung <sup>2)</sup> (typ.) Forward voltage <sup>2)</sup> (max.) $I_F = 20\text{ mA}$	$V_F$ $V_F$	2.0 2.4	2.0 2.4	2.0 2.4	2.0 2.4	V V
Sperrstrom (typ.) Reverse current (max.) $V_R = 3\text{ V}$	$I_R$ $I_R$	0.01 10	0.01 10	0.01 10	0.01 10	$\mu\text{A}$ $\mu\text{A}$
Temperaturkoeffizient von $\lambda_{\text{peak}}$ (typ.) Temperature coefficient of $\lambda_{\text{peak}}$ $I_F = 20\text{ mA}; -10^\circ\text{C} \leq T \leq 100^\circ\text{C}$	$TC_{\lambda_{\text{peak}}}$	0.14	0.13	0.13	0.13	nm/K
Temperaturkoeffizient von $\lambda_{\text{dom}}$ (typ.) Temperature coefficient of $\lambda_{\text{dom}}$ $I_F = 20\text{ mA}; -10^\circ\text{C} \leq T \leq 100^\circ\text{C}$	$TC_{\lambda_{\text{dom}}}$	0.01	0.06	0.07	0.10	nm/K
Temperaturkoeffizient von $V_F$ (typ.) Temperature coefficient of $V_F$ $I_F = 20\text{ mA}; -10^\circ\text{C} \leq T \leq 100^\circ\text{C}$	$TC_V$	-2.0	-1.8	-1.7	-2.5	mV/K
Optischer Wirkungsgrad (typ.) Optical efficiency $I_F = 20\text{ mA}$	$\eta_{\text{opt}}$	5	9	9	9	lm/W

<sup>1)</sup> Wellenlängen werden mit einer Stromeinprägedauer von 25 ms und einer Genauigkeit von  $\pm 1\text{ nm}$  ermittelt.  
Wavelengths are tested at a current pulse duration of 25 ms and a tolerance of  $\pm 1\text{ nm}$ .

<sup>2)</sup> Spannungswerte werden mit einer Stromeinprägedauer von 1 ms und einer Genauigkeit von  $\pm 0.1\text{ V}$  ermittelt.  
Voltages are tested at a current pulse duration of 1 ms and a tolerance of  $\pm 0.1\text{ V}$ .

**Helligkeits-Gruppierungsschema**  
**Luminous Intensity Groups**

<b>Lichtgruppe</b> <b>Luminous Intensity Group</b>	<b>Lichtstärke</b> <b>Luminous Intensity</b> <b>I<sub>v</sub> (mcd)</b>	<b>Lichtstrom</b> <b>Luminous Flux</b> <b>Φ<sub>v</sub> (lm)</b>
N1	28.0 ... 35.5	95 (typ.)
N2	35.5 ... 45.0	120 (typ.)
P1	45.0 ... 56.0	150 (typ.)
P2	56.0 ... 71.0	190 (typ.)
Q1	71.0 ... 90.0	240 (typ.)
Q2	90.0 ... 112.0	300 (typ.)
R1	112.0 ... 140.0	380 (typ.)
R2	140.0 ... 180.0	480 (typ.)
S1	180.0 ... 224.0	600 (typ.)

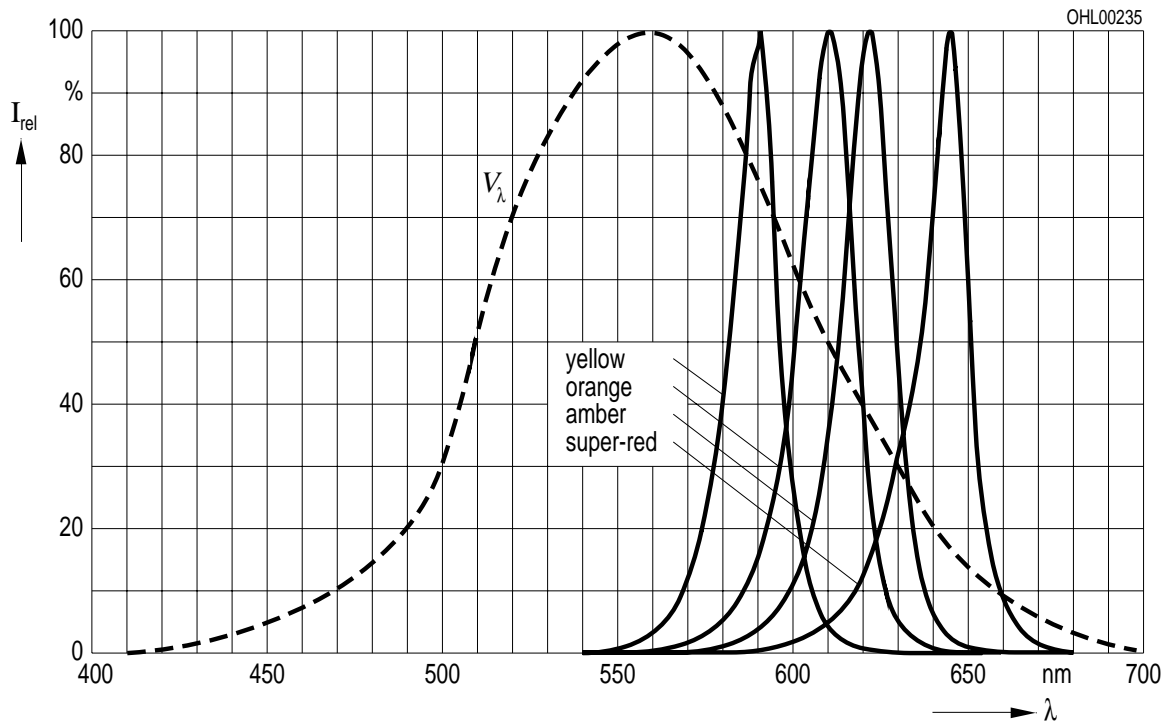
Helligkeitswerte werden mit einer Stromeinprägedauer von 25 ms und einer Genauigkeit von ±11 % ermittelt.  
 Luminous intensity is tested at a current pulse duration of 25 ms and a tolerance of ±11 %.

**Relative spektrale Emission**  $I_{\text{rel}} = f(\lambda)$ ,  $T_A = 25^\circ\text{C}$ ,  $I_F = 20\text{ mA}$

**Relative Spectral Emission**

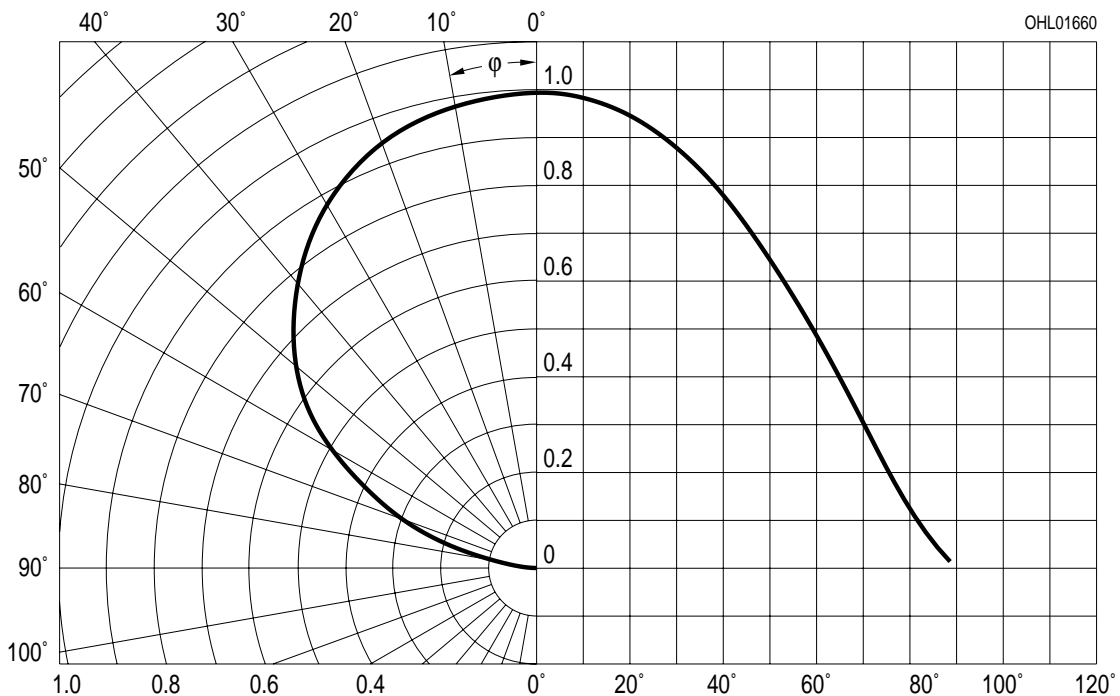
$V(\lambda)$  = spektrale Augenempfindlichkeit

Standard eye response curve



**Abstrahlcharakteristik**  $I_{\text{rel}} = f(\varphi)$

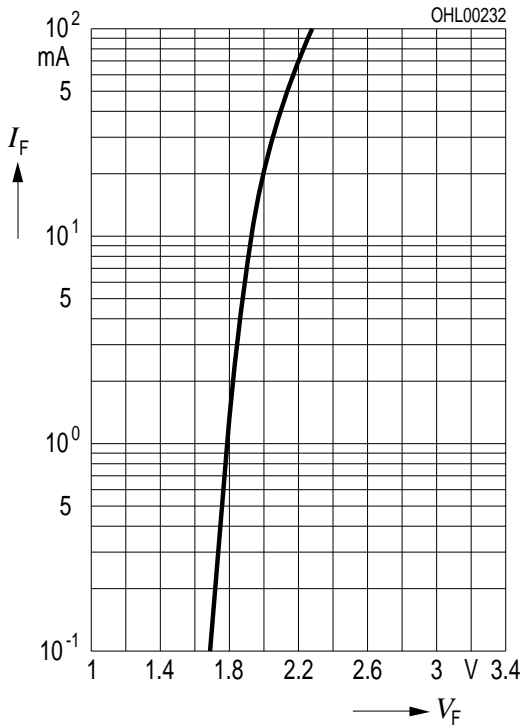
**Radiation Characteristic**



Durchlassstrom  $I_F = f(V_F)$

Forward Current

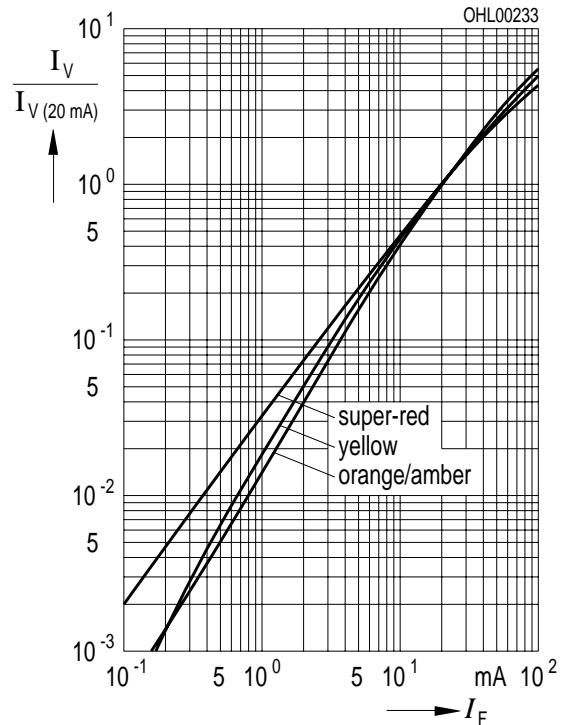
$T_A = 25^\circ\text{C}$



Relative Lichtstärke  $I_V/I_{V(20\text{ mA})} = f(I_F)$

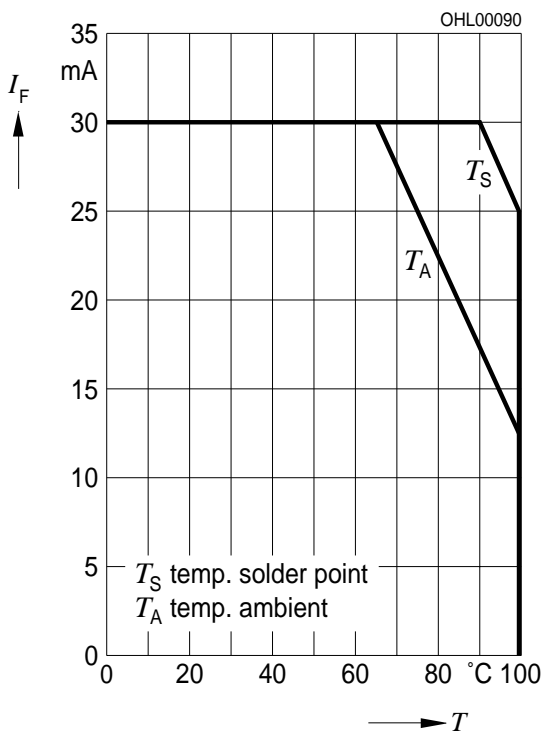
Relative Luminous Intensity

$T_A = 25^\circ\text{C}$



Maximal zulässiger Durchlassstrom  $I_F = f(T)$

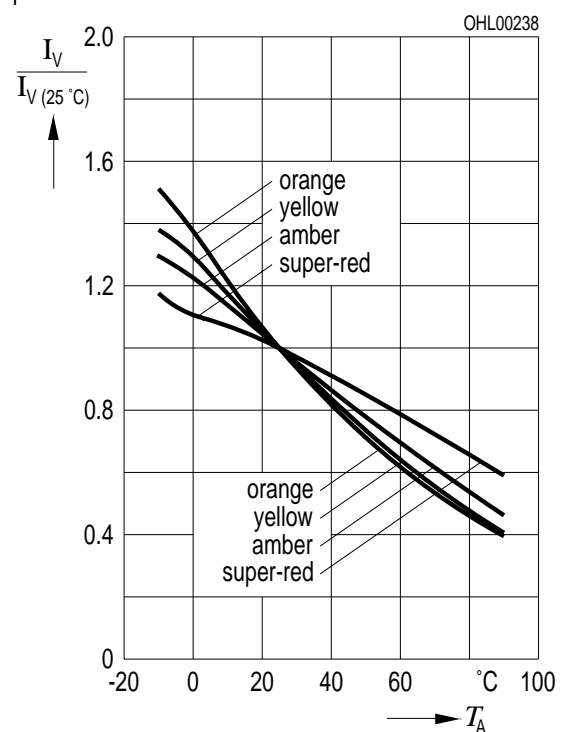
Max. Permissible Forward Current



Relative Lichtstärke  $I_V/I_{V(25^\circ\text{C})} = f(T_A)$

Relative Luminous Intensity

$I_F = 20\text{ mA}$

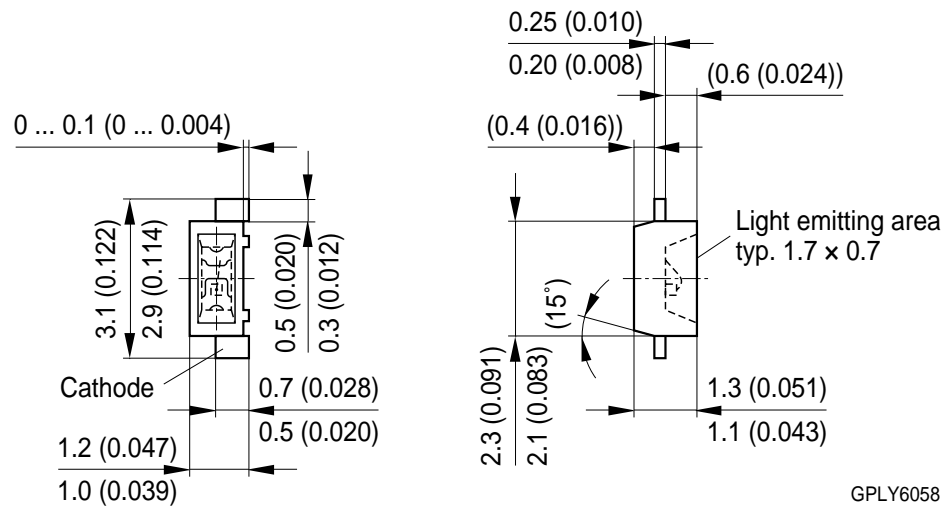


**Zulässige Impulsbelastbarkeit  $I_F = f(t_p)$**   
**Permissible Pulse Handling Capability**  
Duty cycle  $D = \text{parameter}$ ,  $T_A = 25\text{ °C}$   
**LS, LA, LO**

**Zulässige Impulsbelastbarkeit  $I_F = f(t_p)$**   
**Permissible Pulse Handling Capability**  
Duty cycle  $D = \text{parameter}$ ,  $T_A = 25\text{ °C}$   
**LY**



**Maßzeichnung  
Package Outlines**

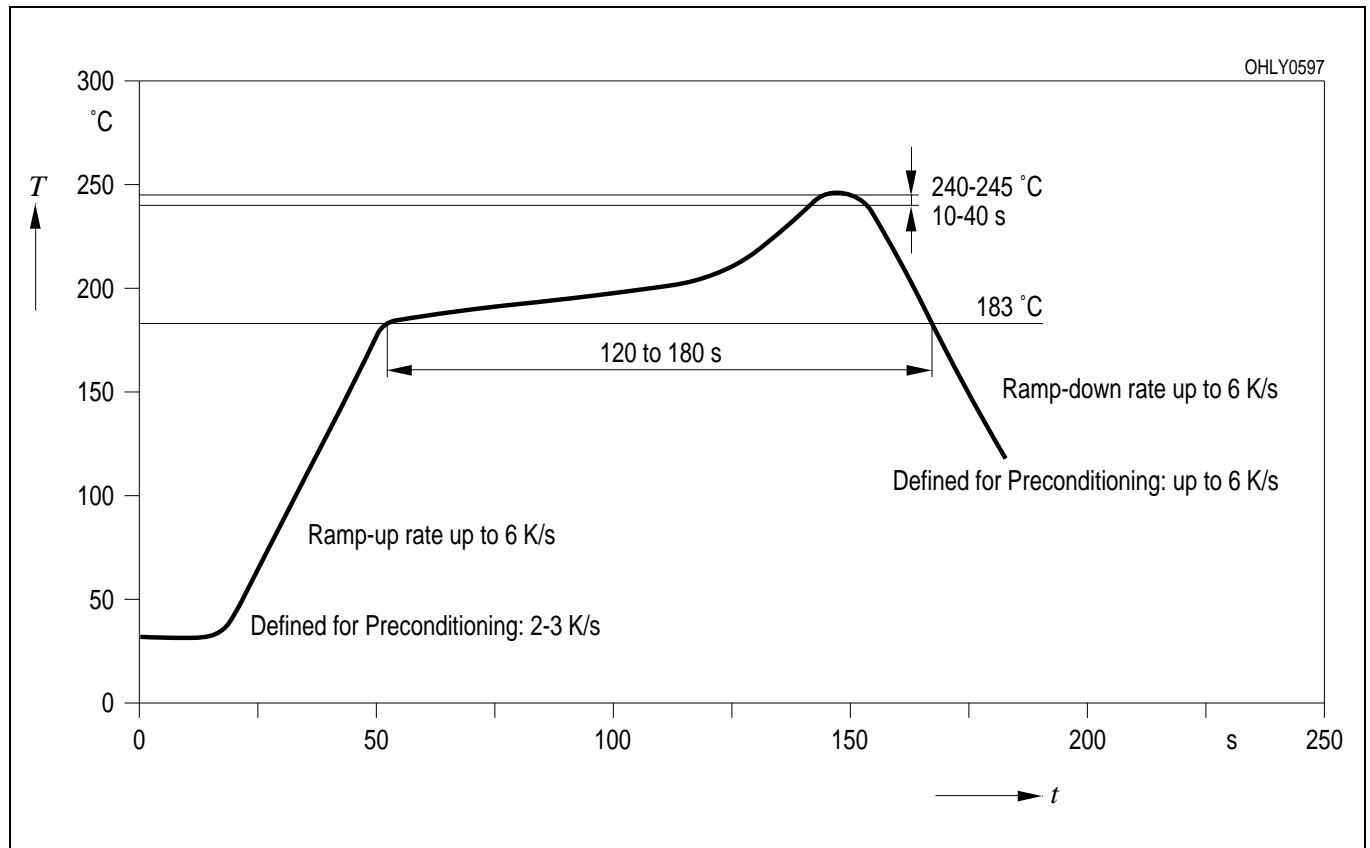


Maße werden wie folgt angegeben: mm (inch) / Dimensions are specified as follows: mm (inch).

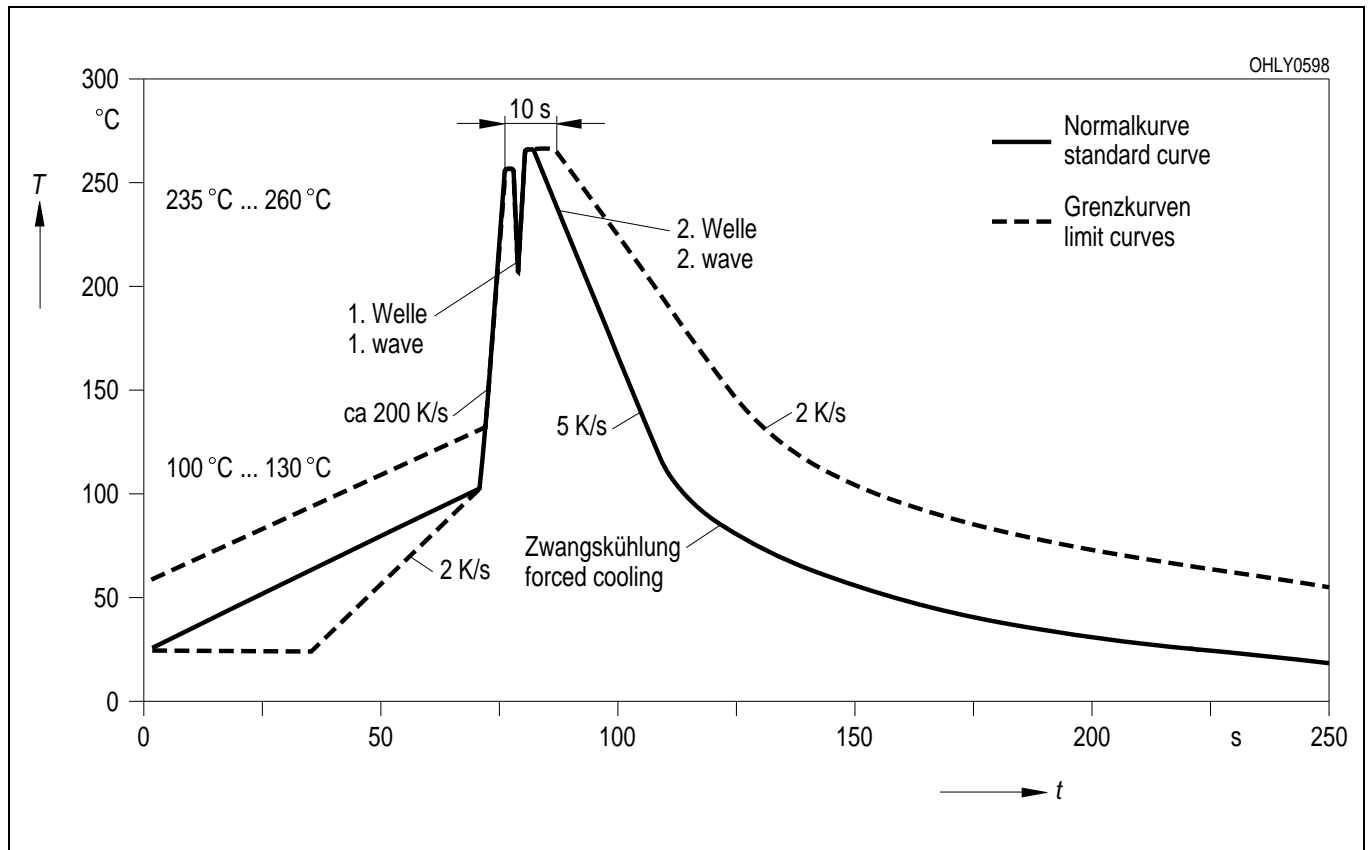
**Gewicht / Approx. weight:** 6 mg

**Lötbedingungen** Vorbehandlung nach JEDEC Level 2  
**Soldering Conditions** Preconditioning acc. to JEDEC Level 2

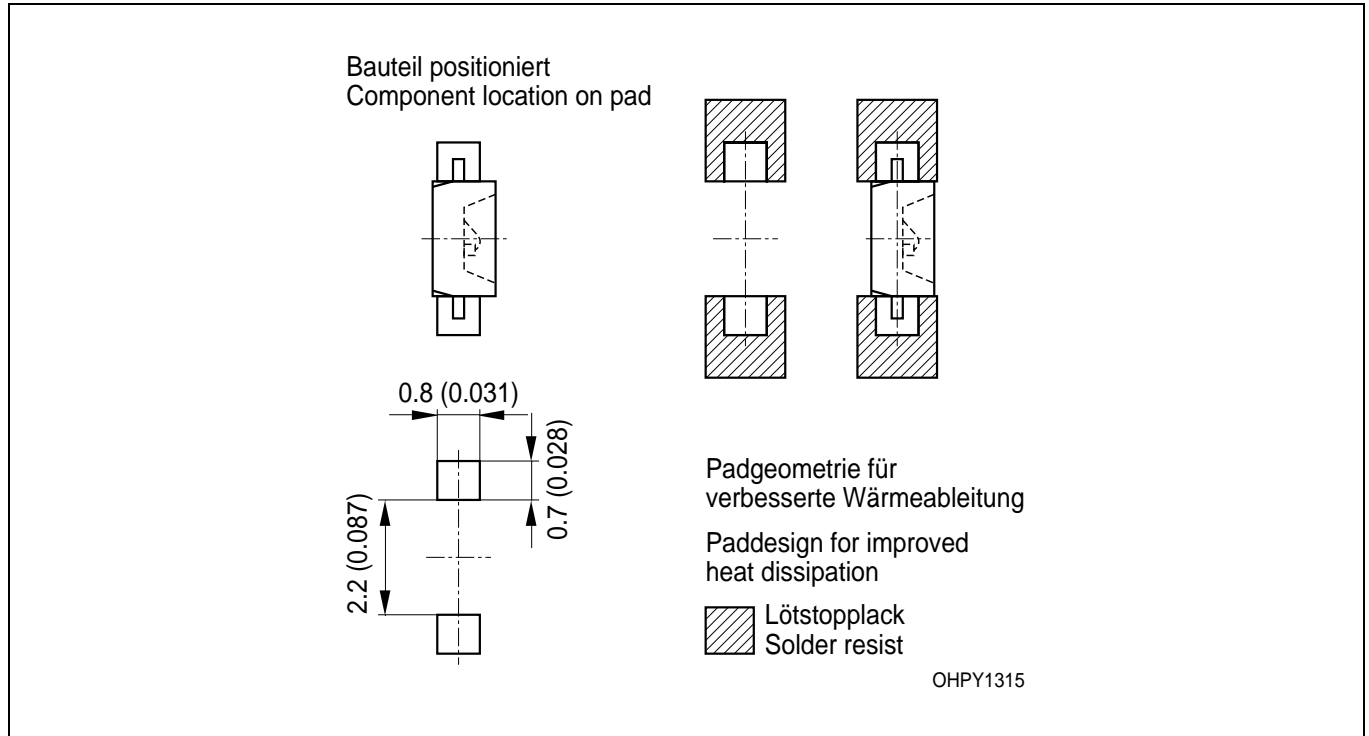
**IR-Reflow Lötprofil** (nach IPC 9501)  
**IR Reflow Soldering Profile** (acc. to IPC 9501)



**Wellenlöten (TTW)** (nach CECC 00802)  
**TTW Soldering** (acc. to CECC 00802)



**Empfohlenes Lötpaddesign** IR Reflow Löten  
**Recommended Solder Pad** IR Reflow Soldering



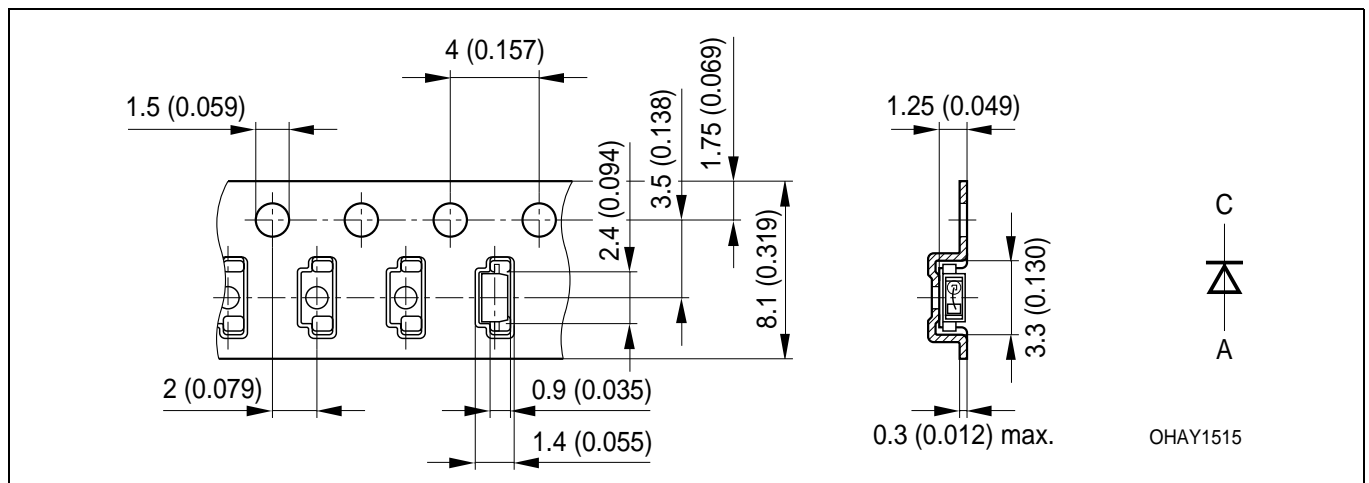
Maße werden wie folgt angegeben: mm (inch) / Dimensions are specified as follows: mm (inch).  
 Gehäuse für Wellenlöten (TTW) geeignet / Package suitable for TTW-soldering

**Gurtung / Polarität und Lage**

Verpackungseinheit 3000/Rolle, ø180 mm  
 oder 10000/Rolle, ø330 mm

**Method of Taping / Polarity and Orientation**

Packing unit 3000/reel, ø180 mm  
 or 10000/reel, ø330 mm



Maße werden wie folgt angegeben: mm (inch) / Dimensions are specified as follows: mm (inch).

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**Revision History: 2001-03-14**

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Previous Version: 2001-03-14

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Page	Subjects (major changes since last revision)

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